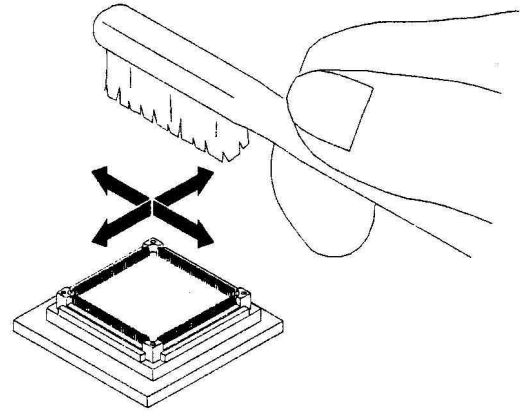


CLIP USE INSTRUCTIONS

CLEANING THE CLIP

Clean the Clip contacts before each installation. Debris on the contacts can interfere with its function.

1. Use a common toothbrush to remove any dust between the contacts. The individual contacts are engineered to be durable; nevertheless take appropriate care when brushing them to avoid damage.
2. Use precision dusting cleaner (also known as inert dusting gas or compressed air in a can) to remove debris loosened by the brushing.



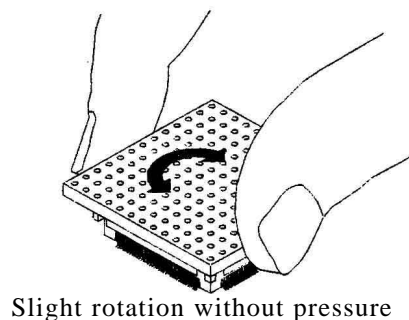
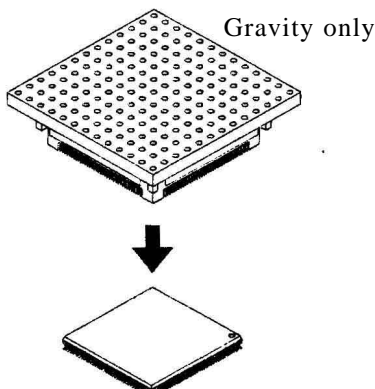
INSTALLING THE CLIP

Extra care is required the first time you install the Clip. Since the chip package has not had previous intrusion between the legs, more force than usual is required during installation. This is due to the fact that there is excess solder from the plating process on the sides of the legs. Once the Clip has been inserted on a chip package far less force will be required.

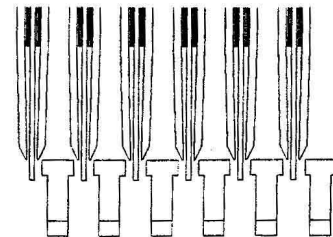
CAUTION Use grounded wrist straps and mats when installing or performing any service to your Clip adaptor. Electrostatic discharge can damage electronic components.

1. Clean the Clip as described above.
2. Allow the Clip to seek its own alignment by resting it on the chip package.
3. Rotate the Clip back and forth, to allow a tactile indication when the sharp tips of the contacts are correctly positioned between the legs of the chip package.

CAUTION Installation of the Clip with any improper alignment can result in damage to the chip package legs and the Clip itself. Avoid damage by ensuring proper positioning as shown. If a transition board or flexible cable are attached to the Clip during installation, the tactile response is diminished and greater care must be taken with initial positioning.



Position contacts between legs



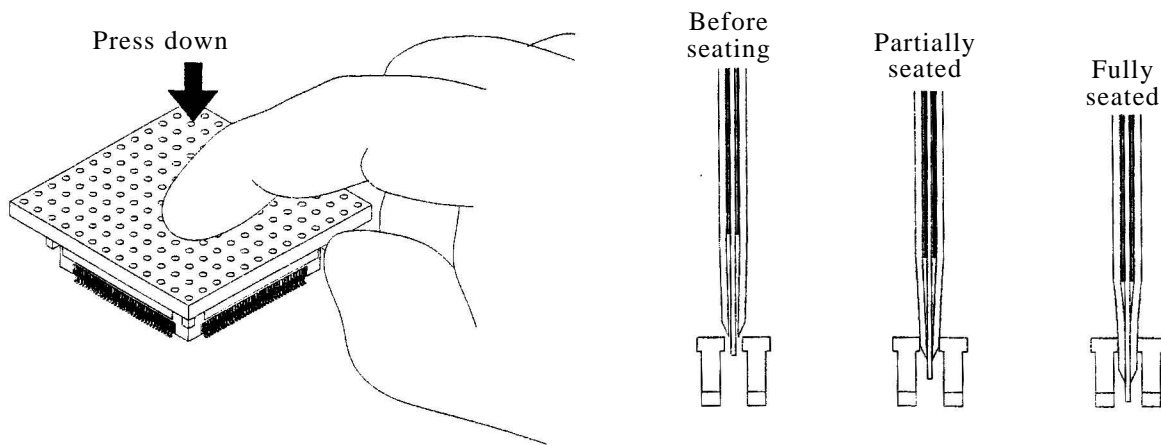
CLIP USE INSTRUCTIONS

INSTALLING THE CLIP

(CONT)

4. Apply a constant downward force after the contacts are centered between the legs. Proper seating of the contacts is proportional to the width of the gap between the legs. The smaller the gap, the more downward force required. The forces required range from 10 to 20 pounds.
5. Apply additional downward pressure to ensure contact between each contact and the adjacent legs of the chip package.

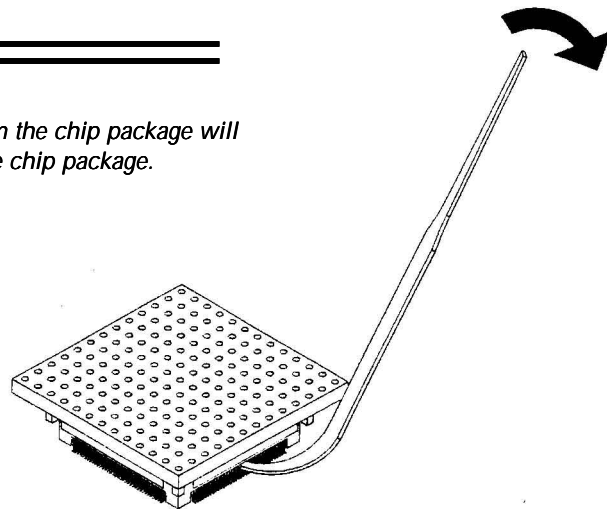
Support under the board where the chip package is located may be helpful when applying this downward force.



REMOVING THE CLIP

CAUTION

Improper removal of the Clip from the chip package will result in damage to the legs of the chip package.



1. Place the extractor tool between the PC board and the bottom rail of the Clip.
2. Pry up slightly on opposite sides of the Clip to loosen it from your chip package.
3. Repeat until you can lift the Clip off of the part without damage to the legs of the chip package.

